

Editorial

Message From the Editor-in-Chief

TODAY I am introducing the first issue in 2021 of the IEEE LETTERS ON ELECTROMAGNETIC COMPATIBILITY PRACTICE AND APPLICATIONS (L-EMCPA), to you. As you might have recognized on the front cover, the L-EMCPA publishes its third volume, i.e., we started our third year of publishing application oriented letters.

There is a saying that a tradition starts with the third replication. In this sense this issue starts the tradition of publishing abstract-reviewed-papers for the annual IEEE Symposium on Electromagnetic Compatibility, Signal and Power Integrity. Authors of abstract-reviewed-papers submit an one-page extended abstract to the technical program of the EMC+SIPI symposium. If the conducted peer-review results in acceptance, the author presents the content at the symposium. After the symposium the authors of abstract-reviewed contributions receive an invitation to submit a full four page abstract-reviewed-paper to the L-EMCPA. Submitted papers are subject of a review by the review board of this journal. Over the last years it turned out that due to the time periods required for writing a full four page paper and reviewing submitted manuscripts, the abstract-reviewed-papers of a symposium are ready for publication in the first quarter of the following year. Therefore, this issue is dedicated for the abstract reviewed-papers, submitted to and presented at the 2020 virtual international IEEE Symposium on Electromagnetic Compatibility, Signal and Power Integrity.

This issue provides you with ten abstract-reviewed-papers. The first paper introduces a test setup that might be used for the characterization of HPEM test environments as well as the interaction of electronic systems with its HPEM environment.

To be honest, I am very interested in learning how many of the readers are interested in getting those test kids to perform own measurements. If I receive sufficient feedback, the editorial board might organize a special issue containing application letters with measurement results and experiences. Other papers published in this issue present experiences with new analysis methods and experiences of designing shielding systems for magnetic resonance imaging. I wish all of you that you find a paper that suits your needs and interests in this special issue.

I hope that through the earnest efforts of the EMC community and their dedication to the field that we will be able to disseminate application-oriented work that will be of high value for EMC engineers and technicians working on system design and in test laboratories. It is with this hope and expectation the Board of Directors of the EMC Society initiated this journey, and they look forward to your wholehearted participation.

Who is interested to share her or his experiences, new applications or solutions with the EMC community is invited to submit a four page letter to the L-EMCPA via <https://mc.manuscriptcentral.com/l-emcpa-ieee>. A template is available on the EMC Society homepage (www.emcs.org) under publications.

FRANK SABATH, *Editor-in-Chief*
Director
Bundeswehr Research Institute for Protective Technologies
and CBRN Protection
Munster, Germany
(e-mail: frank.sabath@ieee.org)